

# PATENT ASSIGNMENT

Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT														
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT														
<b>CONVEYING PARTY DATA</b>															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Moon Il LEE</td> <td>04/25/2011</td> </tr> <tr> <td>Seung Hee HAN</td> <td>04/25/2011</td> </tr> <tr> <td>Ja Ho KOO</td> <td>04/25/2011</td> </tr> <tr> <td>Hyun Soo KO</td> <td>04/25/2011</td> </tr> <tr> <td>Jae Hoon CHUNG</td> <td>04/25/2011</td> </tr> <tr> <td>Bin Chul IHM</td> <td>04/27/2011</td> </tr> </tbody> </table>		Name	Execution Date	Moon Il LEE	04/25/2011	Seung Hee HAN	04/25/2011	Ja Ho KOO	04/25/2011	Hyun Soo KO	04/25/2011	Jae Hoon CHUNG	04/25/2011	Bin Chul IHM	04/27/2011
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<b>RECEIVING PARTY DATA</b>															
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>LG Electronics Inc.</td> </tr> <tr> <td>Street Address:</td> <td>20 Yeouido-dong, Yeongdeungpo-gu</td> </tr> <tr> <td>City:</td> <td>Seoul</td> </tr> <tr> <td>State/Country:</td> <td>REPUBLIC OF KOREA</td> </tr> <tr> <td>Postal Code:</td> <td>150-721</td> </tr> </table>		Name:	LG Electronics Inc.	Street Address:	20 Yeouido-dong, Yeongdeungpo-gu	City:	Seoul	State/Country:	REPUBLIC OF KOREA	Postal Code:	150-721				
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<b>PROPERTY NUMBERS Total: 1</b>															
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<b>CORRESPONDENCE DATA</b>															
Fax Number: (213)623-2211 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 213-623-2221 Email: patent@lhlaw.com Correspondent Name: LEE, HONG, DEGERMAN, KANG & WAIMEY Address Line 1: 660 S. FIGUEROA STREET Address Line 2: Suite 2300 Address Line 4: LOS ANGELES, CALIFORNIA 90017															
<b>ATTORNEY DOCKET NUMBER:</b>	2101-3954														

OP \$40.00 13121936

**501565094**

**PATENT**  
**REEL: 026445 FRAME: 0800**

NAME OF SUBMITTER:

Harry S. Lee

Total Attachments: 2

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ASSIGNMENT

(1-8) *Insert Name(s) of  
Inventor(s)*

(1) MOON IL LEE	(5) JAE HOON CHUNG
(2) SEUNG HEE HAN	(6) BIN CHUL IHM
(3) JA HO KOO	(7)
(4) HYUN SOO KO	(8)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) *Insert name of Assignee*

(9) **LG ELECTRONICS INC.**

(10) *Insert state of Incorporation  
of Assignee*

(10) **Korea**

(11) *Insert address of Assignee*

(11) 20 Yeouido-dong, Yeongdeungpo-gu,  
Seoul, 150-721, Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) *Insert identification of  
Invention, such as Title,  
Case Number or Foreign  
Application Number*

(12) **METHOD FOR PILOT SYMBOL TRANSMISSION IN  
DOWNLINK MIMO SYSTEM  
(Application no. 13/121,936)**

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

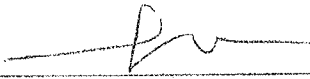
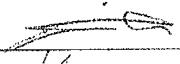
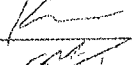
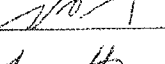
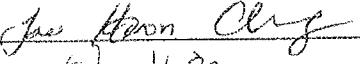
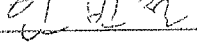
2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints the Attorneys associated with Customer No. 035884 the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: <u>25 April 2011</u>	Signature of Inventor 1 <u></u>
Date: <u>25 April 2011</u>	Signature of Inventor 2 <u></u>
Date: <u>25 April 2011</u>	Signature of Inventor 3 <u></u>
Date: <u>25 April 2011</u>	Signature of Inventor 4 <u></u>
Date: <u>April 25th, 2011</u>	Signature of Inventor 5 <u></u>
Date: <u>Apr 27, 2011</u>	Signature of Inventor 6 <u></u>